

Title (en)
Method and apparatus for nanostructures fabrication

Title (de)
Verfahren und Vorrichtung zur Herstellung von Nanostrukturen

Title (fr)
Procédé et dispositif pour la fabrication de nanostructures

Publication
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Application
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Abstract (en)
[origin: WO0184238A1] A fast method of creating nanostructures comprising the steps of forming one or more electrically-charged regions (5) of predetermined shape on a surface (1) of a first material, by contacting the regions with a stamp for transferring electric charge, and providing electrically charged nanoparticles (7) of a second material, and permitting the particles to flow in the vicinity of the regions, to be deposited on the regions.

IPC 8 full level
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Citation (examination)
UCHIHASHI T ET AL: "Charge storage on thin SrTiO3 film by contact electrification", vol. 33, no. 9B, SPEC. ISSUE, pages 5573 - 5576, XP002149344

Cited by
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